LNJ8L4C18RAA

Surface Mounting Chip LED

3528 (PLCC4) Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	190	mW	
Forward current	I _F	70	mA	
Pulse forward current *	I _{FP}	100	mA	
Reverse voltage	V _R	5	V	
Junction temperature	Tj	125	°C	
Thermal resistance	R _{th}	130	°C/W	
Operating ambient temperature	T _{opr}	-40 to +105	°C	
Storage temperature	T _{stg}	-40 to +125	°C	

Lighting Color

• Red

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

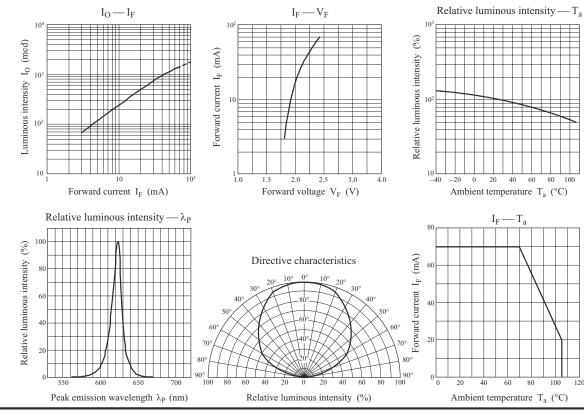
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 50 \text{ mA}$	900	1130	1450	mcd
Reverse current	I _R	$V_R = 5 V$			10	μΑ
Forward voltage *2	V _F	$I_F = 50 \text{ mA}$	2.05	2.30	2.65	V
Luminous flux *1	F	$I_F = 50 \text{ mA}$	(3.36)	(4.20)	(5.40)	lm
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 50 \text{ mA}$		623		nm
Dominant emission wavelength *3	λ _d	$I_F = 50 \text{ mA}$	612	617	624	nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		20		nm

Note) *1: Measurement tolerance: ±11%

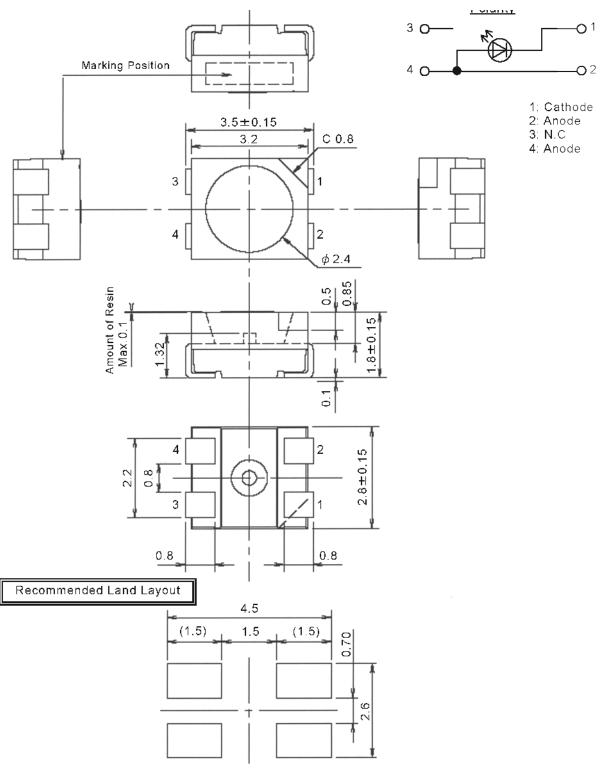
*2: Measurement tolerance: $\pm 0.15 \text{ V}$

*3: Measurement tolerance: ±2 nm



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Package (Unit: mm)



(Note1) Tolerance unless specified: ± 0.1 mm.

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